

## Rochester Electronics Manufactured Components

Rochester branded components are manufactured using either die/wafers purchased from the original suppliers or Rochester wafers recreated from the original IP. All recreations are done with the approval of the OCM.

Parts are tested using original factory test programs or Rochester developed test solutions to guarantee product meets or exceed the OCM data sheet.

## Quality Overview

- ISO-9001
- AS9120 certification
- Qualified Manufacturers List (QML) MIL-PRF-35835
  - Class Q Military
  - Class V Space Level
- Qualified Suppliers List of Distributors (QSLD)
  - Rochester is a critical supplier to DLA and meets all industry and DLA standards.

Rochester Electronics, LLC is committed to supplying products that satisfy customer expectations for quality and are equal to those originally supplied by industry manufacturers.

The original manufacturer's datasheet accompanying this document reflects the performance and specifications of the Rochester manufactured version of this device. Rochester Electronics guarantees the performance of its semiconductor products to the original OEM specifications. 'Typical' values are for reference purposes only. Certain minimum or maximum ratings may be based on product characterization, design, simulation, or sample testing.

**2.7GHz UpConverter with Gain Control**



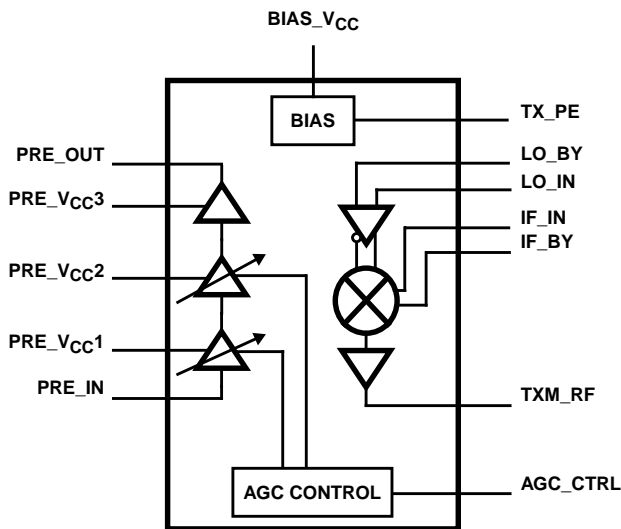
The HFA3664 UpConverter with Gain Control is a monolithic bipolar PRISM<sup>®</sup> device for up conversion applications in the 2.3GHz to 2.7GHz range.

Manufactured in the Intersil UHF1X process, the device consists of a double balanced mixer followed by a variable gain power preamp. An energy saving, TTL Compatible, power enable input provides on/off bias current control to the mixer and amplifier. The device requires low drive levels from the local oscillator and is housed in a small outline 20 lead SSOP package ideally suited for PCMCIA card applications.

**Ordering Information**

PART NUMBER	TEMP. RANGE (°C)	PACKAGE	PKG. NO.
HFA3664IA	-40 to 85	20 Ld SSOP	M20.15
HFA3664IA96	-40 to 85	Tape and Reel	

**Block Diagram**



**POWER CONTROL TRUTH TABLE**

STATE	TX_PE
Power Down - Energy Saving Mode	Low
Transmit Mode	High

**Features**

- RF Frequency Range . . . . . 2.3GHz to 2.7GHz
- IF Operation . . . . . 10MHz to 400MHz
- Gain Control Range . . . . . .20dB
- Single Supply Operation. . . . . 2.7V to 5.5V
- High Output 1dB Compression. . . . . 6dBm
- High Power Gain . . . . . .18dB
- Power Enable/Disable Control

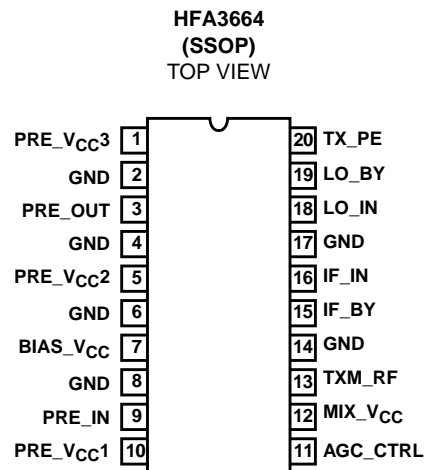
**Applications**

- Wireless Local Loop Systems
- PCMCIA Wireless Transceiver
- Wireless Local Area Network Modems
- CDMA/TDMA Packet Protocol Radios
- Full Duplex Transceivers
- Portable Battery Powered Equipment

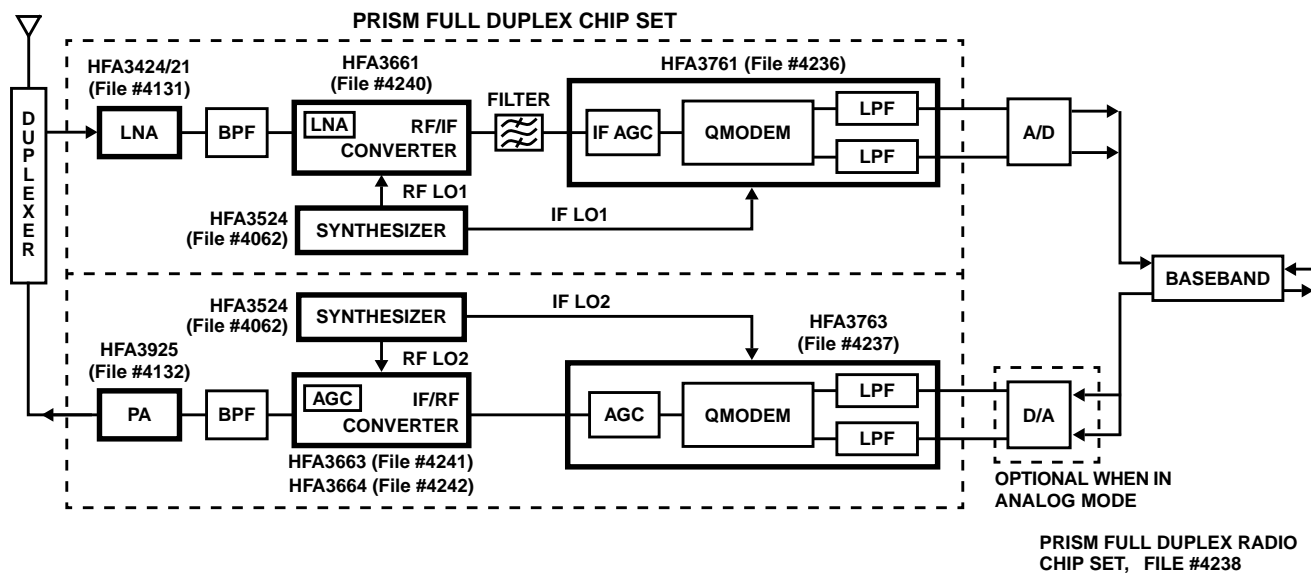
**Related Literature**

- Technical Brief TB363 "Guidelines for Handling and Processing Moisture Sensitive Surface Mount Devices (SMDs)"

**Pinout**



Typical Application Diagram



Pin Descriptions

NAME	DESCRIPTION
LO_IN	Local Oscillator Input.
LO_BY	Local Oscillator Input Bypass (AC coupled to GND).
PRE_IN	Power Pre-Amplifier Input.
PRE_OUT	Power Pre-Amplifier Output.
PRE_VCC1	Power Pre-Amplifier 1st Stage Positive Power Supply. Use high quality RF decoupling capacitors.
PRE_VCC2	Power Pre-Amplifier 2nd Stage Positive Power Supply. Use high quality RF decoupling capacitors.
PRE_VCC3	Power Pre-Amplifier 3rd Stage Positive Power Supply. Use high quality RF decoupling capacitors.
BIAS_VCC	LO Buffer, Bias, Mixer and AGC Control Positive Power Supply. Requires an isolation coil to V <sub>CC</sub> .
MIX_VCC	Transmit Mixer Output Stage Positive Power Supply. Use high quality RF decoupling capacitors.
RX_PE	Power Enable Control Input. Refer to the Power Control Truth Table.
TXM_RF	Transmit Mixer RF Output.
IF_IN	Transmit Mixer Positive IF Input. Requires external bias resistor to V <sub>CC</sub> .
IF_BY	Transmit Mixer Negative IF Input (AC coupled to GND).
GND	Circuit Ground Pins (Qty 6). Internally connected with the exception of pin 17.

# HFA3664

## Absolute Maximum Ratings

Supply Voltage . . . . . -0.3 to 6.0V  
 Voltage on Any Other Pin . . . . . -0.3 to  $V_{CC}$  0.3V

## Operating Conditions

Supply Voltage Range . . . . . 2.7V to 5.5V

## Thermal Information

Thermal Resistance (Typical, Note 1)  $\theta_{JA}$  (°C/W)  
 20 Lead SSOP . . . . . 110  
 Package Power Dissipation at 70°C  
 20 Lead SSOP . . . . . 0.7W  
 Maximum Junction Temperature (Plastic Package) . . . . . 150°C  
 Maximum Temperature Range . . . . .  $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$   
 Maximum Storage Temperature Range . . . . .  $-65^{\circ}\text{C} \leq T_A \leq 150^{\circ}\text{C}$   
 Maximum Lead Temperature (Soldering 10s) . . . . . 300°C  
 (Lead Tips Only)

**CAUTION:** Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

### NOTE:

- $\theta_{JA}$  is measured with the component mounted on a low effective thermal conductivity test board in free air. See Tech Brief TB379 for details.

## Electrical Specifications $V_{CC} = 5.5\text{V}$ , LO = 2400MHz, IF = 100MHz, RF = 2500MHz, $Z_O = 50\Omega$ , Unless Otherwise Specified

PARAMETER	SYMBOL	(NOTE 2) TEST LEVEL	TEMP (°C)	MIN	TYP	MAX	UNITS
<b>CASCADED CHARACTERISTICS</b> (-3dB Loss RF Image Filter with 35dB LO Suppression, LO_IN = 2400MHz/-6dBm, IF_IN = 100MHz/-30dBm, AGC_CTRL = 0.7V (Max Gain))							
Cascaded Output 1dB Compression	CTX_P1D	B	25	6	7.5	-	dBm
Cascaded Output Third Order Intercept	CTX_IP3	C	25	-	14	-	dBm
Cascaded Power Gain	CTX_PG	B	25	18	23	-	dB
Cascaded Power Gain Flatness (2.3GHz to 2.7GHz)	CTX_PGF	C	25	-2.5	0	+2.5	dB
Cascaded LO Leakage	CTX_LEAK	B	25	-	-23.8	-	dBm
<b>LO INPUT CHARACTERISTICS</b> (LO_IN = 2400MHz/-6dBm, all unused inputs and outputs are terminated into 50Ω)							
LO Input Frequency Range	LO_f	B	25	1.9	-	2.29	GHz
LO Input Drive Level	LO_dr	A	25	-	-6	-	dBm
LO Input VSWR	LO_SWR	A	25	1.0:1	1.62:1	2.3:1	-
LO Input Return Loss	LO_IRL	A	25	8.09	12.5	-	dB
<b>TRANSMIT MIXER CHARACTERISTICS</b> (LO_IN = 2400MHz/-6dBm, TXM_IF = 100MHz/-30dBm)							
IF Input Frequency Range	TXM_IFf	B	25, 85	10	-	400	MHz
IF Input VSWR	TXM_SWR	A	25	-	1.22:1	2.0:1	-
IF Input Return Loss	TXM_IRL	A	25	9.5	20	-	dB
Power Conversion Gain (Note 3)	$V_{CC} = 5.5\text{V}$ TXM_PGH	A	25	3.0	4.5	-	dB
Transmit Mixer LO Leakage	TXM_LEAK	A	25	-	-20	-10	dBm
RF Output Frequency Range	TXM_RFf	B	25, 85	2.4	-	2.7	GHz
RF Output VSWR	TXM_OSWR	A	25	1.01	1.68:1	2.3:1	-
RF Output Return Loss	TXM_ORL	A	25	8.09	12	-	dB
RF Output 1dB Compression (Note 3)	$V_{CC} = 5.5\text{V}$ TXM_P1DH	A	25	-12	-7.5	-	dBm
RF Output Third Order Intercept	TXM_IP3	C	25	-	-1.0	-	dBm
Transmit Mixer Noise Figure	TXM_NF	B	25	-	18	-	dB

## HFA3664

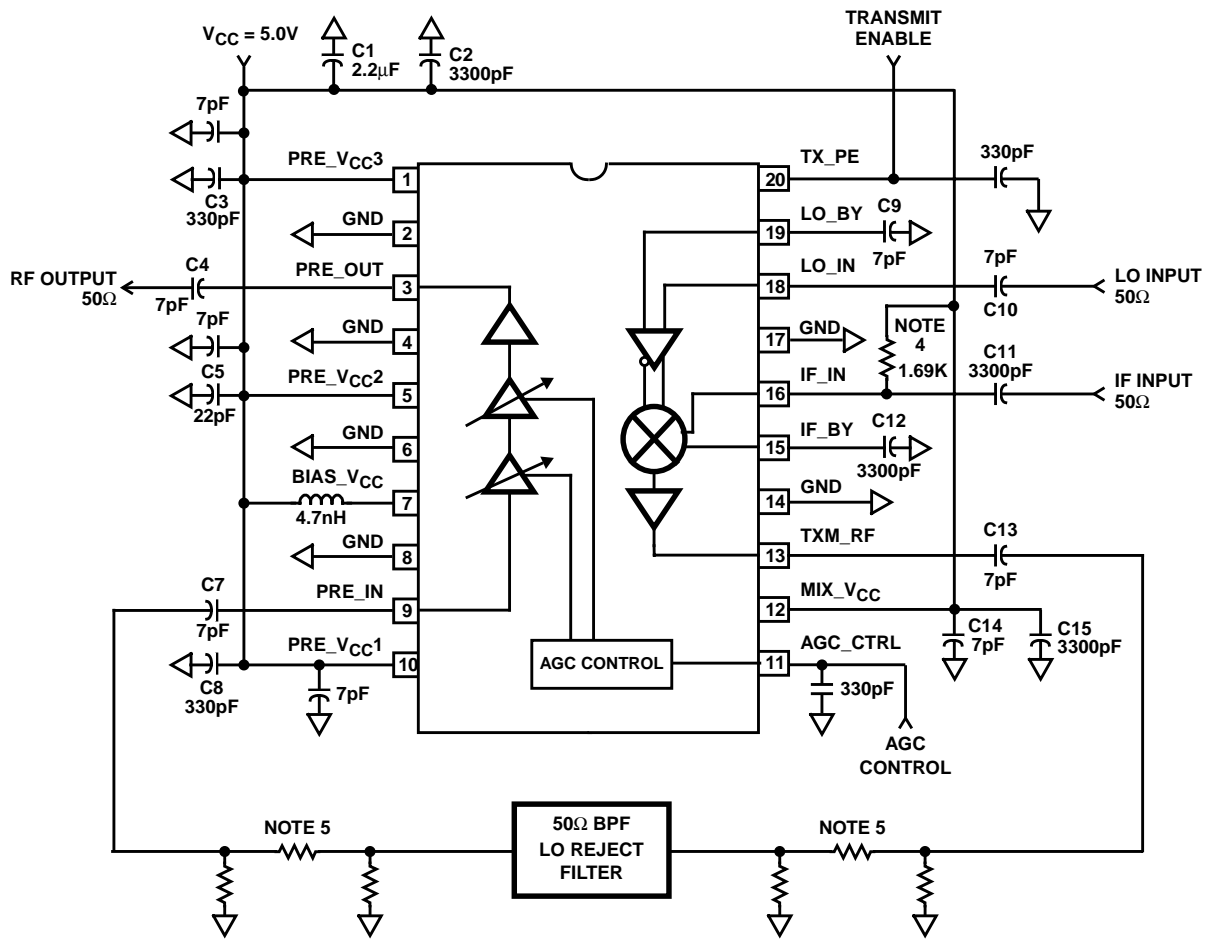
**Electrical Specifications**  $V_{CC} = 5.5V$ , LO = 2400MHz, IF = 100MHz, RF = 2500MHz,  $Z_O = 50\Omega$ ,  
Unless Otherwise Specified **(Continued)**

PARAMETER	SYMBOL	(NOTE 2) TEST LEVEL	TEMP (°C)	MIN	TYP	MAX	UNITS
<b>TRANSMIT POWER PREAMP CHARACTERISTICS</b> (PRE_IN = 2400MHz/-30dBm, AGC_CTRL = 0.7V (Max Gain))							
Frequency Range	PRE_f	B	25	2.3	-	2.7	GHz
Power Gain (AGC_CTRL = 0.7V)	$V_{CC} = 5.5V$ PRE_PGH	A	25	19	24	29	dB
Pre-Amp Noise Figure (Max Gain)	PRE_NF	B	25	-	8	-	dB
Pre-Amp AGC Range (Max - Min Gain)	PRE_AGC	A	25	20	30	-	dB
AGC Control Voltage Range	AGC_V	A	25	0.7	-	1.7	V
AGC Control Linearity	AGC_LIN	B	25	-	5:1	-	-
AGC Settling Time (Min to Max Gain)	AGC_T1	B	25	-	8.0	-	$\mu$ S
AGC Settling Time (Max to Min Gain)	AGC_T2	B	25	-	0.1	-	$\mu$ S
Pre-Amp RF Output 1dB Compression	$V_{CC} = 5.5V$ PRE_P1DH	A	25	4	8	-	dBm
RF Output Third Order Intercept	PRE_IP3	C	25	-	14	-	dBm
Input VSWR	PRE_ISWR	A	25	1.0:1	2.0:1	3.0:1	-
Input Return Loss	PRE_IRL	A	25	6	7	-	dB
Output VSWR	PRE_OSWR	A	25	1.0:1	1.28:1	2.3:1	-
Output Return Loss	PRE_ORL	A	25	8.09	20	-	dB
<b>POWER SUPPLY AND LOGIC CHARACTERISTICS</b>							
Voltage Supply Range	$V_{CC}$	A	25	-	5.5	-	V
Supply Current ( $V_{CC} = 5.5V$ )	$I_{CC\ HI}$	A	25	90	103	110	mA
	$I_{CC\ HI\ T}$	C	Full	-	-	110	mA
Power Down Supply Current ( $V_{CC} = 5.5V$ )	$I_{CC\ PD}$	A	25	2	3.3	4	mA
Logic Input Low Level	$V_{IL}$	A	25	-0.2	-	0.8	V
Logic Input High Level	$V_{IH}$	A	25	2.0	-	$V_{CC}$	V
Logic Low Input Bias Current ( $V_{PE} = 0V$ , $V_{CC} = 5.5V$ )	$I_{B\_LO}$	A	25	-5	-0.1	5	$\mu$ A
Logic High Input Bias Current ( $V_{PE} = 5.5V$ , $V_{CC} = 5.5V$ )	$I_{B\_HI}$	A	25	-5	0.6	5	$\mu$ A
Vagc High Input Bias Current ( $V_{agc} = 2.1V$ , $V_{CC} = 5.5V$ )	$I_{vagc\_HI}$	A	25	10	200	400	$\mu$ A
Vagc Low Input Bias Current ( $V_{agc} = 0.7V$ , $V_{CC} = 5.5V$ )	$I_{vagc\_LO}$	A	25	-400	-235	-10	$\mu$ A
Power Enable Time (50% $V_{PE}$ to 90% $I_{CC}$ )	PEt	B	25	-	5	10	$\mu$ s
Power Disable Time (50% $V_{PE}$ to 10% $I_{CC}$ )	PDt	B	25	-	0.1	10	$\mu$ s

**NOTES:**

- Test Level: A = 100% production tested, B = Typical or Limit based on characterization data, C = Design information, goal or condition.
- Bias Resistor at pin 16 changes according to the relationship mentioned in Note 4 of the Typical Applications Circuit.

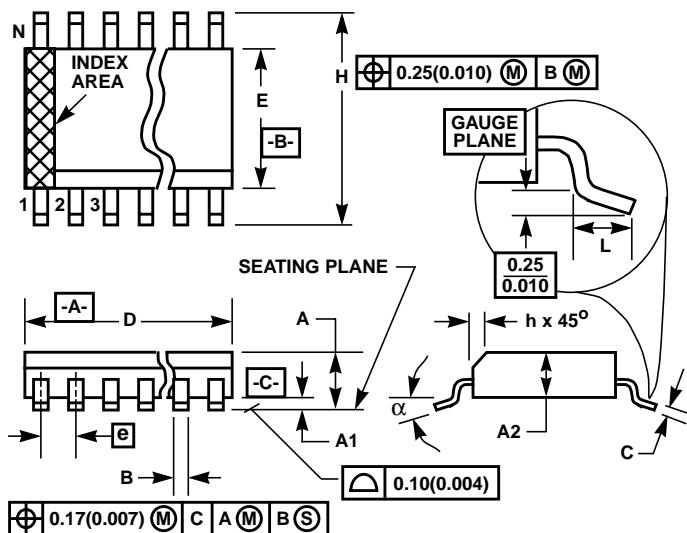
Typical Application Circuit



NOTES:

4. Required external resistor for Mixer biasing. Value optimized for 2.7mA bias current with  $R = (V_{CC} - 0.93) / 2.7\text{mA}$ . Most Mixer cell characteristics like Gain, NF etc., can be affected when biasing is outside the optimum value.
5. The combination of these attenuator pads and the Band Pass Filter insertion loss shall bring the overall Cascaded Gain at the desired frequency of operation from 21dB to 22dB for best performance. The selection of these values is optional. The total gain, LO feedthru, Mixer and Pre-amplifier interaction (stability) and output compression point performances can be manipulated according to the user needs.

## Shrink Small Outline Plastic Packages (SSOP)



### NOTES:

1. Symbols are defined in the "MO Series Symbol List" in Section 2.2 of Publication Number 95.
2. Dimensioning and tolerancing per ANSI Y14.5M-1982.
3. Dimension "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion and gate burrs shall not exceed 0.15mm (0.006 inch) per side.
4. Dimension "E" does not include interlead flash or protrusions. Interlead flash and protrusions shall not exceed 0.25mm (0.010 inch) per side.
5. The chamfer on the body is optional. If it is not present, a visual index feature must be located within the crosshatched area.
6. "L" is the length of terminal for soldering to a substrate.
7. "N" is the number of terminal positions.
8. Terminal numbers are shown for reference only.
9. Dimension "B" does not include dambar protrusion. Allowable dambar protrusion shall be 0.10mm (0.004 inch) total in excess of "B" dimension at maximum material condition.
10. Controlling dimension: INCHES. Converted millimeter dimensions are not necessarily exact.

### M20.15

#### 20 LEAD SHRINK NARROW BODY SMALL OUTLINE PLASTIC PACKAGE

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.053	0.069	1.35	1.75	-
A1	0.004	0.010	0.10	0.25	-
A2	-	0.061	-	1.54	-
B	0.008	0.012	0.20	0.30	9
C	0.007	0.010	0.18	0.25	-
D	0.337	0.344	8.56	8.74	3
E	0.150	0.157	3.81	3.98	4
e	0.025 BSC		0.635 BSC		-
H	0.228	0.244	5.80	6.19	-
h	0.0099	0.0196	0.26	0.49	5
L	0.016	0.050	0.41	1.27	6
N	20		20		7
$\alpha$	0°	8°	0°	8°	-

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